

ABSTRACT

A resin molding apparatus includes: a first molding mold provided with a first member and a second member configured to move relative to the first member, and configured to form a cavity by the first member and the second member; a second molding mold configured to hold a substrate; and a mask member so as to be relatively immovable with respect to the first member, configured to make contact with a portion of the substrate when the first molding mold and the second molding mold are clamped, and formed with a flow portion through which a resin material existing in the cavity and pressurized by the second member is capable of flowing.

(FIG. 8)